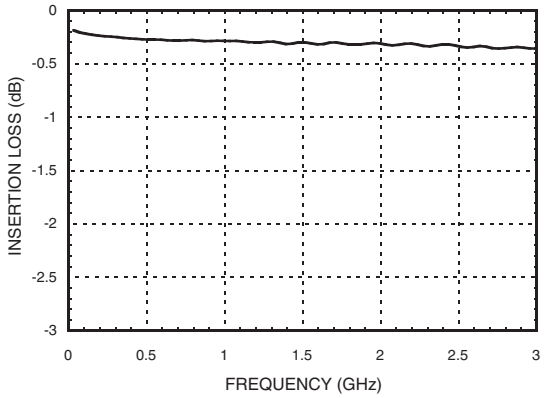
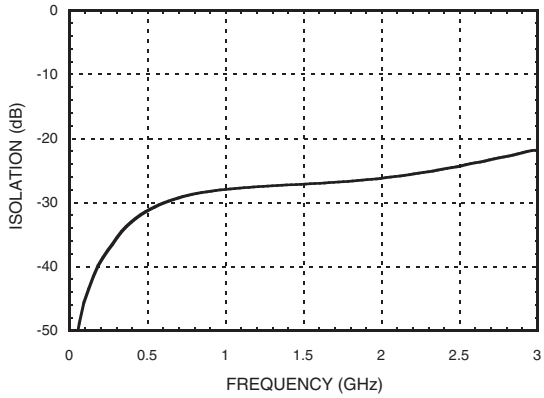
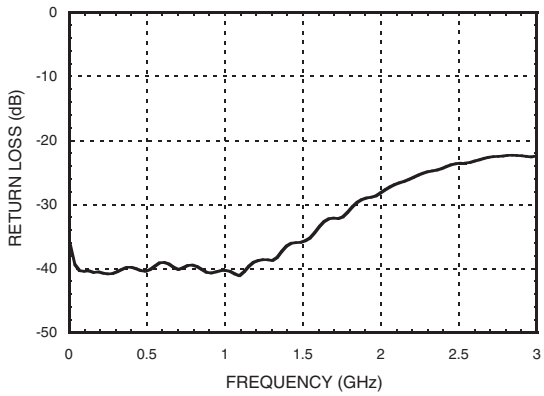
Insertion Loss



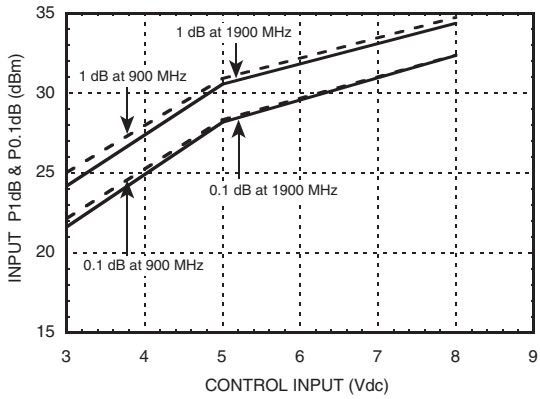
Isolation



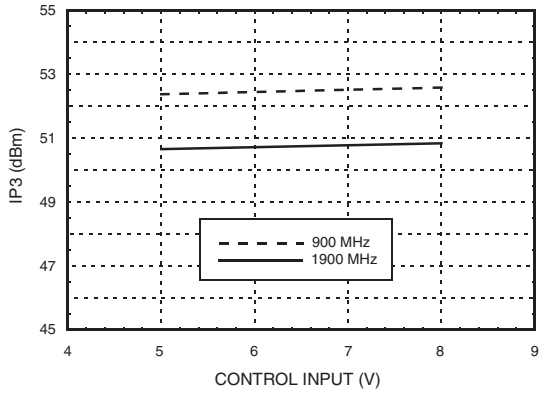
Return Loss



Input 0.1 and 1.0 dB Compression vs. Control Voltage



Input Third Order Intercept Point vs. Control Voltage



Distortion vs. Control Voltage

Control Input	Third Order Intercept (dBm) +7 dBm Each Tone	
(Vdc)	900 MHz	1900 MHz
+5	52	50
+8	52	51

Compression vs. Control Voltage

	Carrier at 900 MHz		Carrier at 1900 MHz	
Control Input	Input Power for 0.1 dB Compression	Input Power for 1.0 dB Compression	Input Power for 0.1 dB Compression	Input Power for 1.0 dB Compression
(Volts)	(dBm)	(dBm)	(dBm)	(dBm)
+3	21	24	22	25
+5	27	30	27	31
+8	32	34	32	34

Truth Table

***Control Input Voltage Tolerances are ± 0.2 Vdc.**

Control Input*		Control Current		Signal Path State	
A (Vdc)	B (Vdc)	Ia (µA)	Ib (µA)	RF to RF1	RF to RF2
0	+3	-3	3	ON	OFF
+3	0	3	-3	OFF	ON
0	+5	-5	5	ON	OFF
+5	0	5	-5	OFF	ON
0	+8	-32	32	ON	OFF
+8	0	32	-32	OFF	ON

Caution: Do not operate in 1 dB compression at power levels above +31 dBm (Vctl = +5 Vdc) and do not "hot switch" power levels greater than +20dBm (Vctl = +5 Vdc).

DC blocks are required at ports RFC, RF1 and RF2.

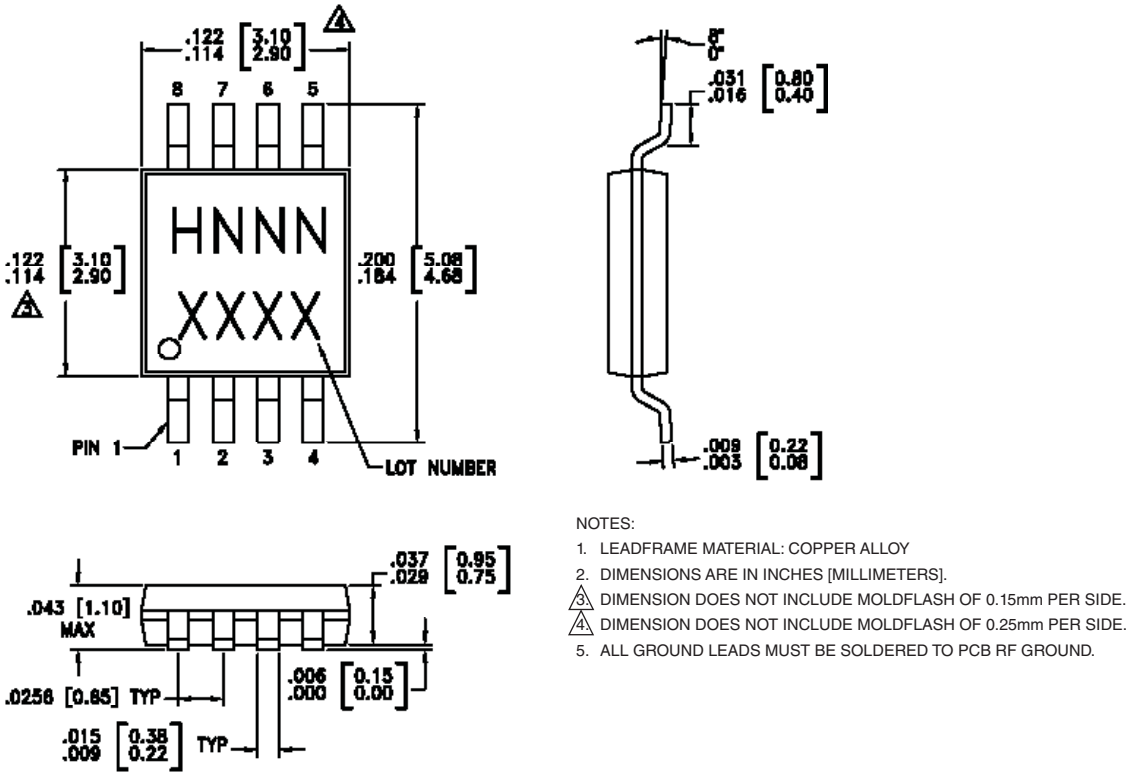
For price, delivery and to place orders: Hittite Microwave Corporation, 20 Alpha Road, Chelmsford, MA 01824
Phone: 978-250-3343 Fax: 978-250-3373 Order On-line at www.hittite.com
Application Support: Phone: 978-250-3343 or apps@hittite.com

Absolute Maximum Ratings

Max. Input Power V_{CTL} = 0/+8V	0.5 GHz 0.5 - 2 GHz	+27 dBm +34 dBm
Control Voltage Range (A & B)		-0.2 to +12 Vdc
Storage Temperature		-65 to +150 °C
Operating Temperature		-40 to +85 °C
ESD Sensitivity (HBM)		Class 1A

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



NOTES:

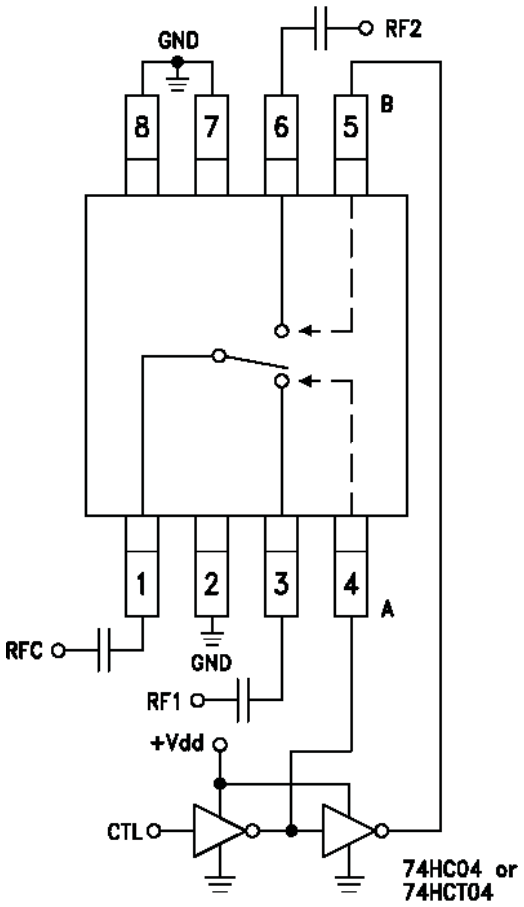
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC190AMS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H190A XXXX
HMC190AMS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H190A XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX

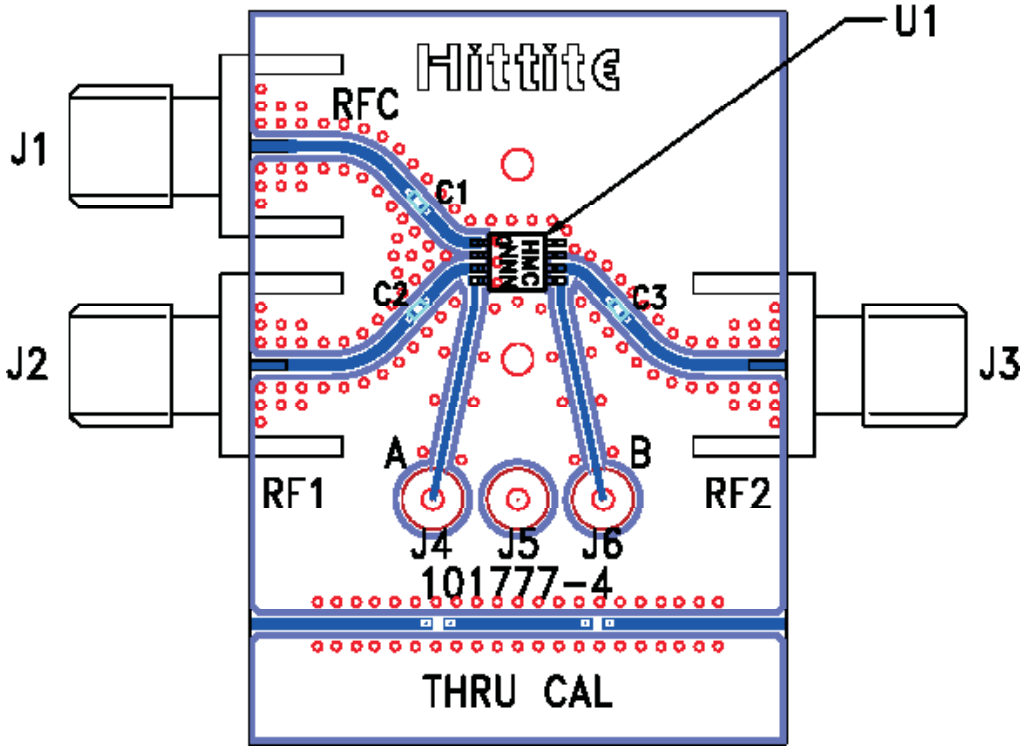
Typical Application Circuit



Notes:

1. Set logic gate and switch Vdd = +3V to +5V and use HCT series logic to provide a TTL driver interface.
2. Control inputs A/B can be driven directly with CMOS logic (HC) with Vdd of 5 to 8 Volts applied to the CMOS logic gates.
3. DC blocking capacitors are required for each RF port as shown. Capacitor value determines lowest frequency of operation.
4. Highest RF signal power capability is achieved with Vdd = +8V and A/B set to 0/+8V.

Evaluation Circuit Board



List of Materials for Evaluation PCB 101779 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
J4 - J6	DC Pin
C1 - C3	330 pF Capacitor, 0402 Pkg.
U1	HMC190AMS8(E) SPDT Switch
PCB [2]	101777 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 Ohm impedance and the package ground leads and package bottom should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.